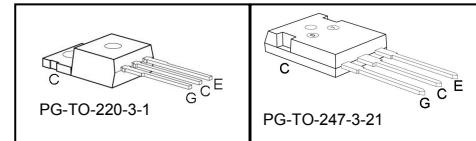
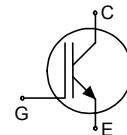


Low Loss IGBT in TrenchStop® and Fieldstop technology

- Very low $V_{CE(sat)}$ 1.5 V (typ.)
- Maximum Junction Temperature 175 °C
- Short circuit withstand time – 5μs
- Designed for :
 - Frequency Converters
 - Uninterrupted Power Supply
- TrenchStop® and Fieldstop technology for 600 V applications offers :
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
 - very high switching speed
 - low $V_{CE(sat)}$
- Positive temperature coefficient in $V_{CE(sat)}$
- Low EMI
- Low Gate Charge
- Qualified according to JEDEC¹ for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	V_{CE}	I_C	$V_{CE(sat), T_j=25^\circ C}$	$T_{j,max}$	Marking	Package
IGP50N60T	600 V	50 A	1.5 V	175 °C	G50T60	PG-T0-220-3-1
IGW50N60T	600 V	50 A	1.5 V	175 °C	G50T60	PG-T0-247-3-21

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	600	V
DC collector current, limited by $T_{j,max}$	I_C		A
$T_C = 25^\circ C$		100	
$T_C = 100^\circ C$		50	
Pulsed collector current, t_p limited by $T_{j,max}$	I_{Cpuls}	150	
Turn off safe operating area ($V_{CE} \leq 600V$, $T_j \leq 175^\circ C$)	-	150	
Gate-emitter voltage	V_{GE}	± 20	V
Short circuit withstand time ²⁾ $V_{GE} = 15V$, $V_{CC} \leq 400V$, $T_j \leq 150^\circ C$	t_{SC}	5	μs
Power dissipation $T_C = 25^\circ C$	P_{tot}	333	W
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+175	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

¹ J-STD-020 and JESD-022

²⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.45	K/W
Thermal resistance, junction – ambient	R_{thJA}	PG-TO-220-3-1 PG-TO-247-3-21	62 40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}, I_C=0.2\text{mA}$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(\text{sat})}$	$V_{GE} = 15\text{V}, I_C=50\text{A}$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	-	1.5	2.0	
Gate-emitter threshold voltage	$V_{GE(\text{th})}$	$I_C=0.8\text{mA}, V_{CE}=V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	I_{CES}	$V_{CE}=600\text{V}, V_{GE}=0\text{V}$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	-	-	40	μA
-			-	-	1000	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0\text{V}, V_{GE}=20\text{V}$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20\text{V}, I_C=50\text{A}$	-	31	-	S
Integrated gate resistor	R_{Gint}			-		Ω

Dynamic Characteristic

Input capacitance	C_{iss}	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	-	3140	-	pF
Output capacitance	C_{oss}		-	200	-	
Reverse transfer capacitance	C_{rss}		-	93	-	
Gate charge	Q_{Gate}	$V_{CC}=480\text{V}, I_C=50\text{A}$ $V_{GE}=15\text{V}$	-	310	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E	PG-TO-220-3-1 PG-TO-247-3-21	-	7	-	nH
Short circuit collector current ¹⁾	$I_{C(SC)}$	$V_{GE}=15\text{V}, t_{SC}\leq 5\mu\text{s}$ $V_{CC} = 400\text{V}, T_j \leq 150^\circ\text{C}$	-	458.3	-	A

¹⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$, $V_{CC}=400\text{V}$, $I_C=50\text{A}$, $V_{GE}=0/15\text{V}$, $R_G=7 \Omega$, $L_\sigma^{(1)}=103\text{nH}$, $C_\sigma^{(1)}=39\text{pF}$ Energy losses include “tail” and diode reverse recovery. ²⁾	-	26	-	ns
Rise time	t_r		-	29	-	
Turn-off delay time	$t_{d(off)}$		-	299	-	
Fall time	t_f		-	29	-	
Turn-on energy	E_{on}		-	1.2	-	mJ
Turn-off energy	E_{off}		-	1.4	-	
Total switching energy	E_{ts}		-	2.6	-	

Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=175^\circ\text{C}$, $V_{CC}=400\text{V}$, $I_C=50\text{A}$, $V_{GE}=0/15\text{V}$, $R_G=7 \Omega$, $L_\sigma^{(1)}=103\text{nH}$, $C_\sigma^{(1)}=39\text{pF}$ Energy losses include “tail” and diode reverse recovery. ²⁾	-	27	-	ns
Rise time	t_r		-	33	-	
Turn-off delay time	$t_{d(off)}$		-	341	-	
Fall time	t_f		-	55	-	
Turn-on energy	E_{on}		-	1.8	-	mJ
Turn-off energy	E_{off}		-	1.8	-	
Total switching energy	E_{ts}		-	3.6	-	

¹⁾ Leakage inductance L_σ and Stray capacity C_σ due to dynamic test circuit in Figure E.

²⁾ Includes Reverse Recovery Losses from IKW50N60T due to dynamic test circuit in Figure E.

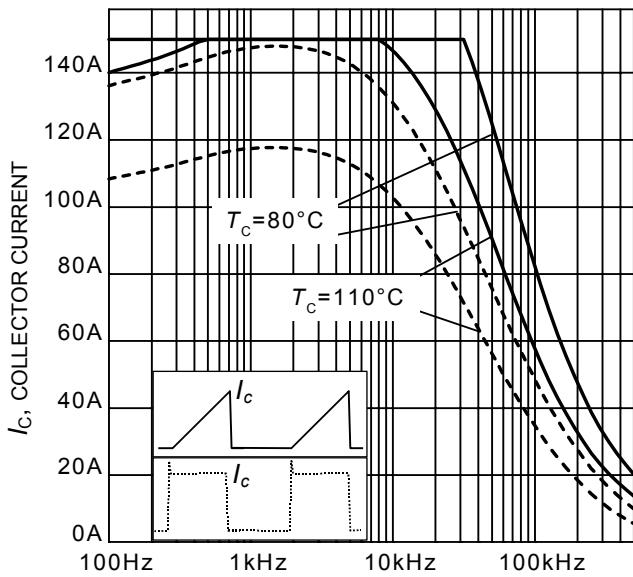

 f , SWITCHING FREQUENCY

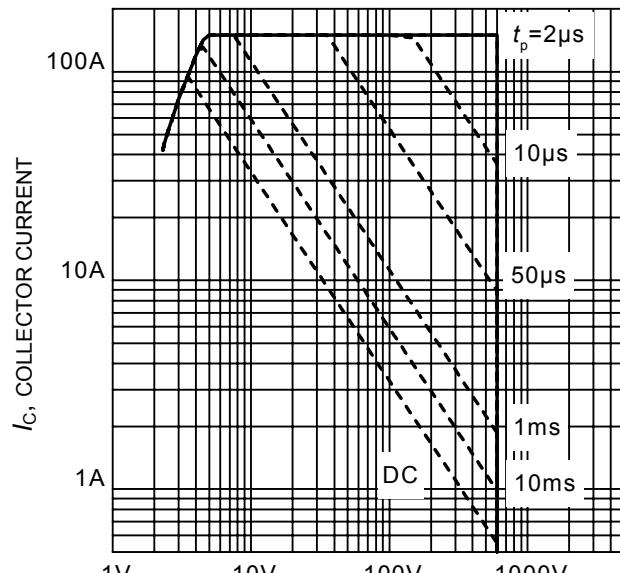
Figure 1. Collector current as a function of switching frequency
 $(T_j \leq 175^\circ\text{C}, D = 0.5, V_{CE} = 400\text{V}, V_{GE} = 0/+15\text{V}, R_G = 7\Omega)$

 V_{CE} , COLLECTOR-EMITTER VOLTAGE

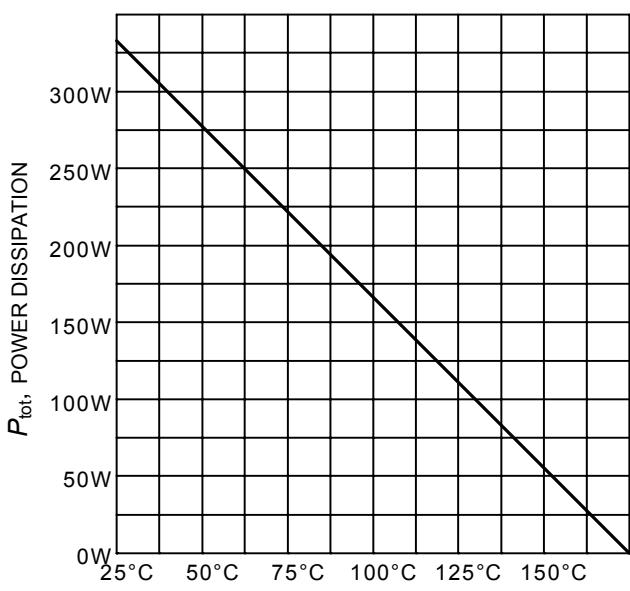
Figure 2. Safe operating area
 $(D = 0, T_C = 25^\circ\text{C}, T_j \leq 175^\circ\text{C}, V_{GE} = 15\text{V})$

 T_C , CASE TEMPERATURE

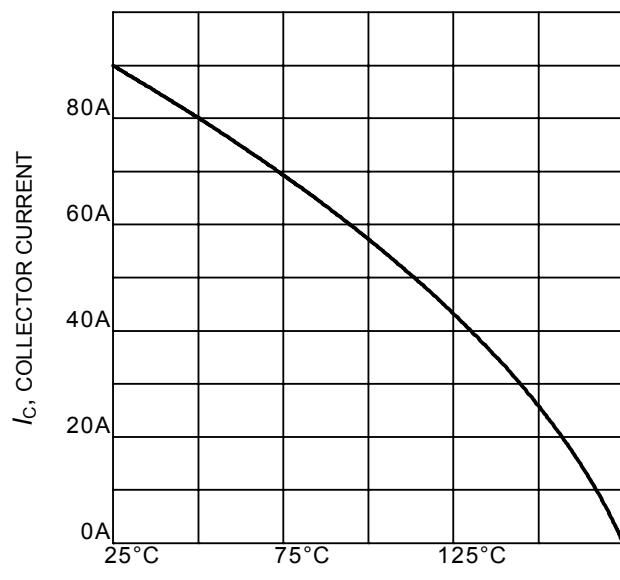
Figure 3. Power dissipation as a function of case temperature
 $(T_j \leq 175^\circ\text{C})$

 T_C , CASE TEMPERATURE

Figure 4. Collector current as a function of case temperature
 $(V_{GE} \geq 15\text{V}, T_j \leq 175^\circ\text{C})$

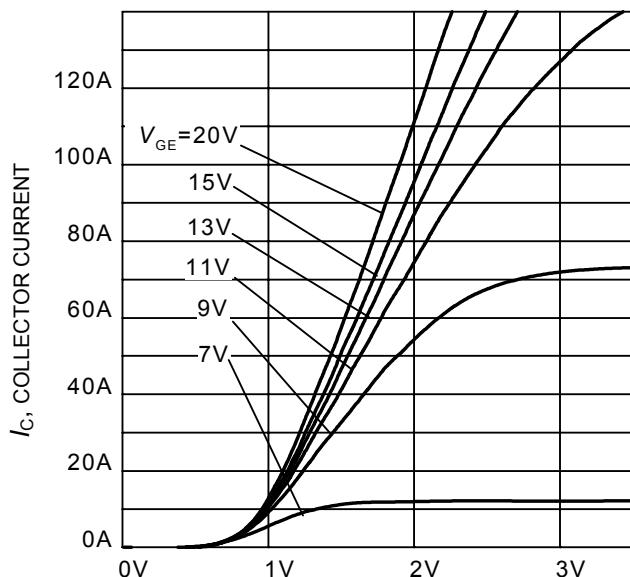


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

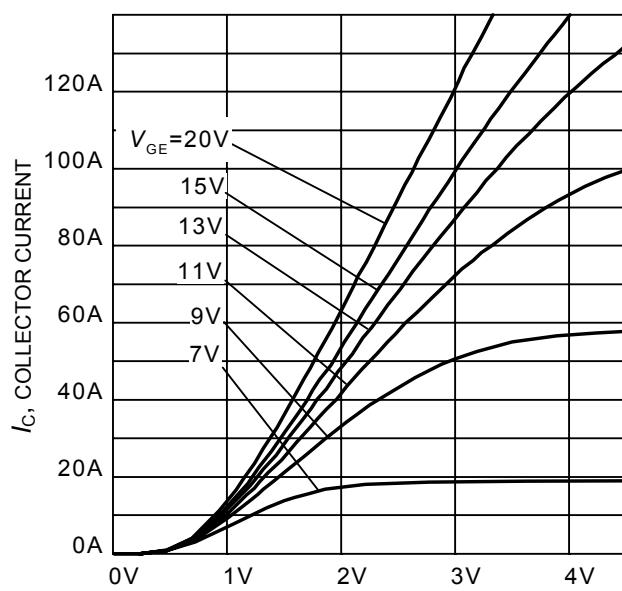


Figure 6. Typical output characteristic
($T_j = 175^\circ\text{C}$)

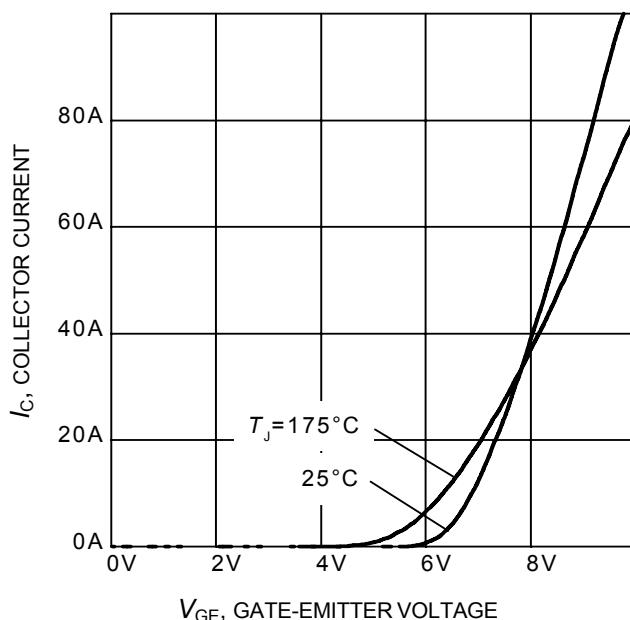


Figure 7. Typical transfer characteristic
($V_{CE}=20\text{V}$)

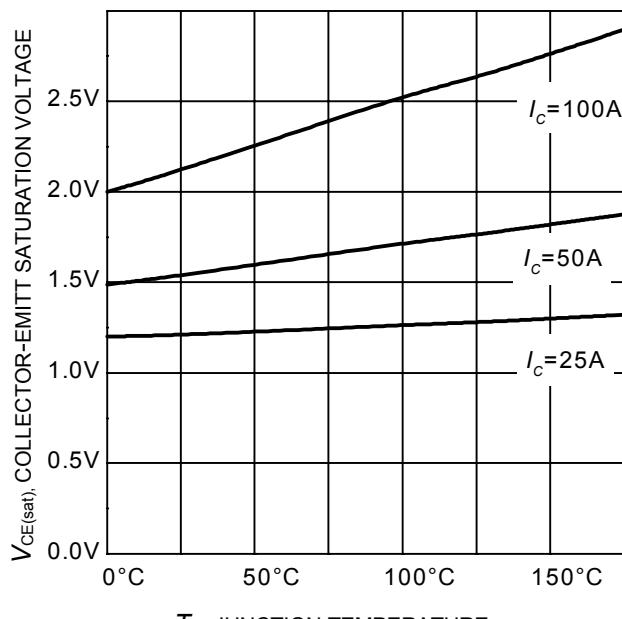


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

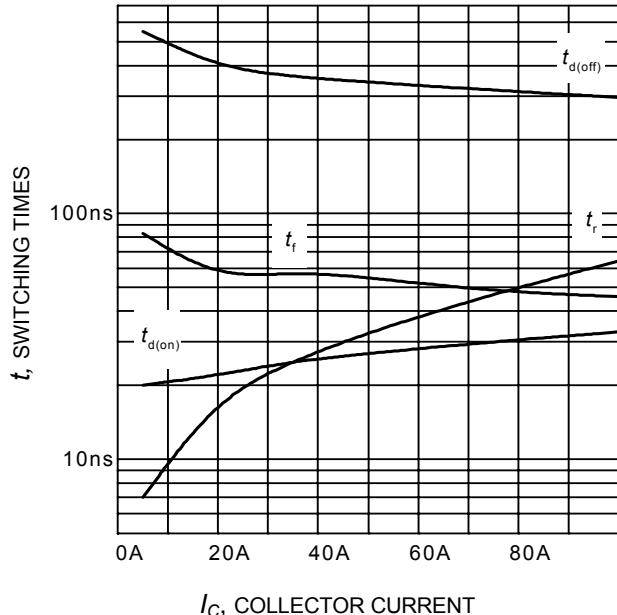

 I_C , COLLECTOR CURRENT

Figure 9. Typical switching times as a function of collector current (inductive load, $T_J = 175^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/15\text{V}$, $R_G = 7\Omega$, Dynamic test circuit in Figure E)

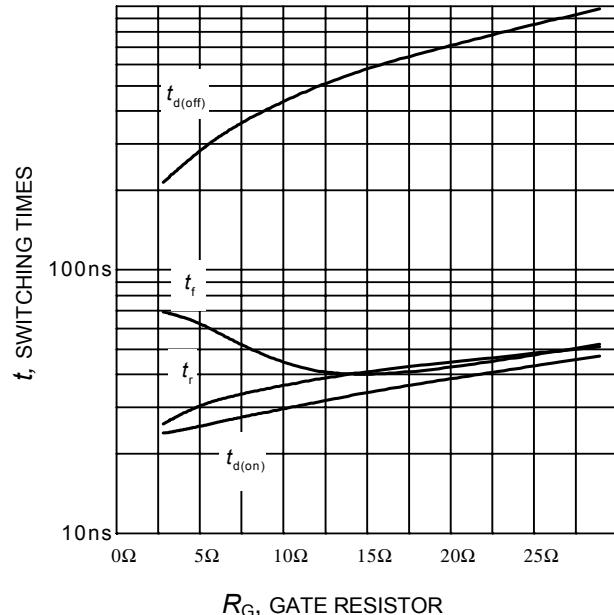

 R_G , GATE RESISTOR

Figure 10. Typical switching times as a function of gate resistor (inductive load, $T_J = 175^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/15\text{V}$, $I_C = 50\text{A}$, Dynamic test circuit in Figure E)

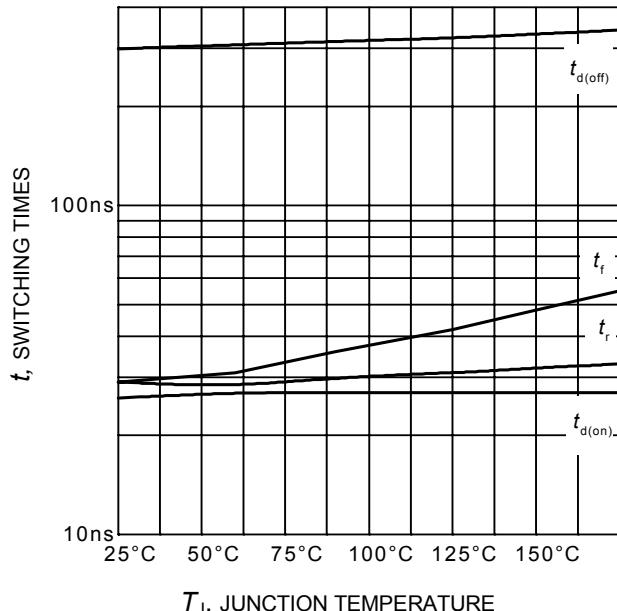

 T_J , JUNCTION TEMPERATURE

Figure 11. Typical switching times as a function of junction temperature (inductive load, $V_{CE} = 400\text{V}$, $V_{GE} = 0/15\text{V}$, $I_C = 50\text{A}$, $R_G = 7\Omega$, Dynamic test circuit in Figure E)

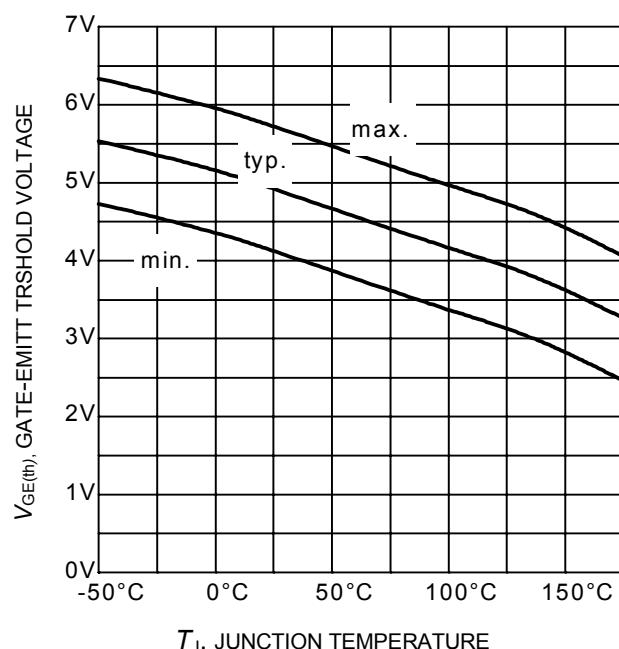


Figure 12. Gate-emitter threshold voltage as a function of junction temperature ($I_C = 0.8\text{mA}$)

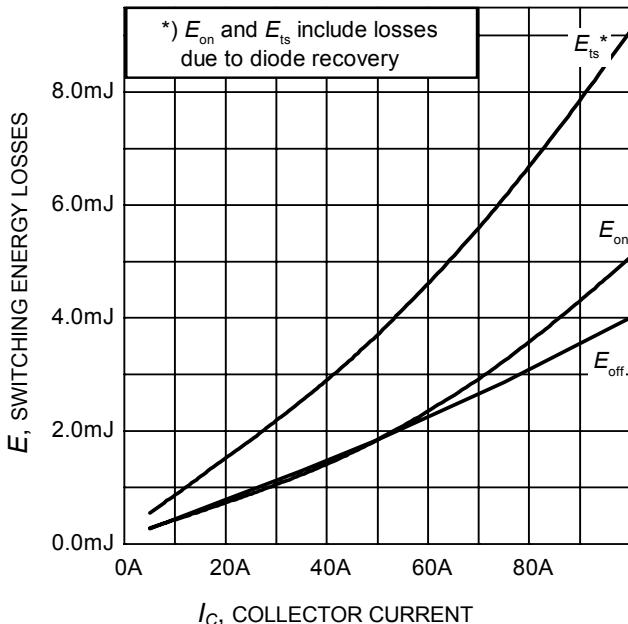


Figure 13. Typical switching energy losses as a function of collector current
(inductive load, $T_J = 175^\circ\text{C}$,
 $V_{CE} = 400\text{V}$, $V_{GE} = 0/15\text{V}$, $R_G = 7\Omega$,
Dynamic test circuit in Figure E)

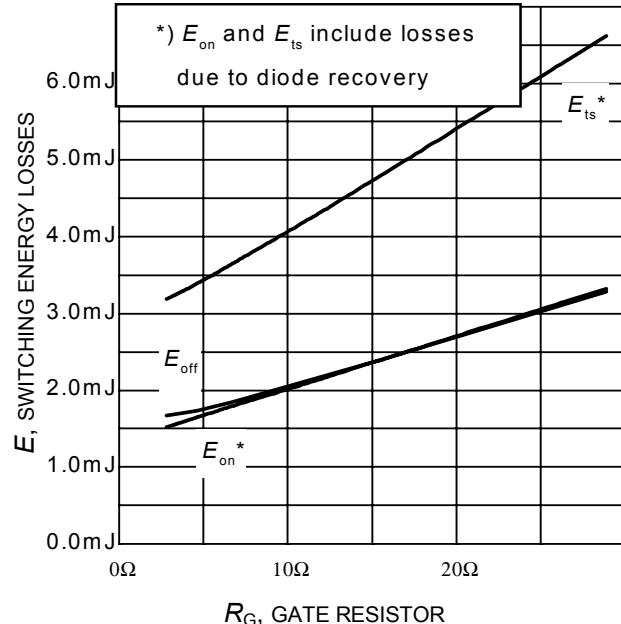


Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, $T_J = 175^\circ\text{C}$,
 $V_{CE} = 400\text{V}$, $V_{GE} = 0/15\text{V}$, $I_C = 50\text{A}$,
Dynamic test circuit in Figure E)

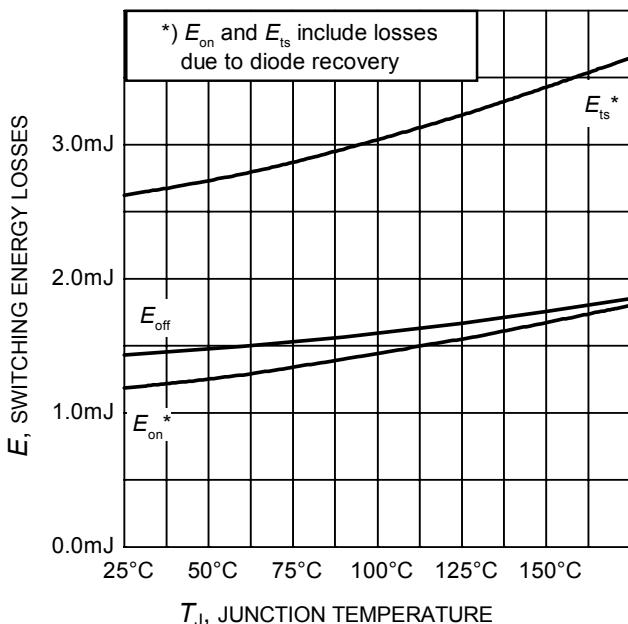


Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE} = 400\text{V}$,
 $V_{GE} = 0/15\text{V}$, $I_C = 50\text{A}$, $R_G = 7\Omega$,
Dynamic test circuit in Figure E)

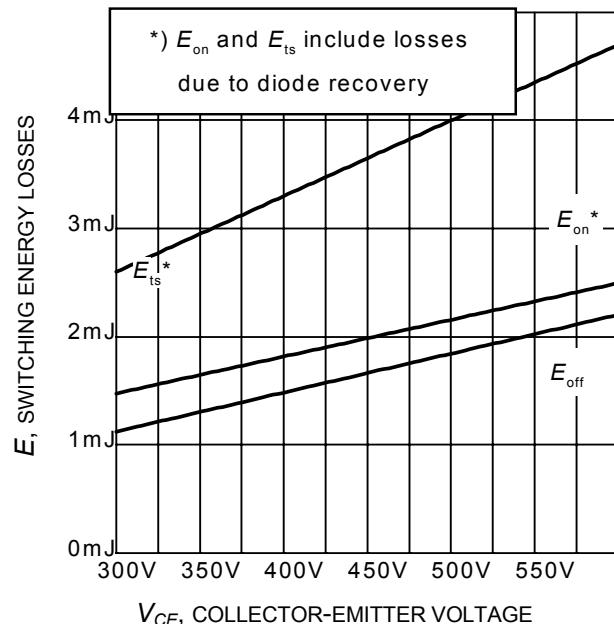


Figure 16. Typical switching energy losses as a function of collector-emitter voltage
(inductive load, $T_J = 175^\circ\text{C}$,
 $V_{GE} = 0/15\text{V}$, $I_C = 50\text{A}$, $R_G = 7\Omega$,
Dynamic test circuit in Figure E)

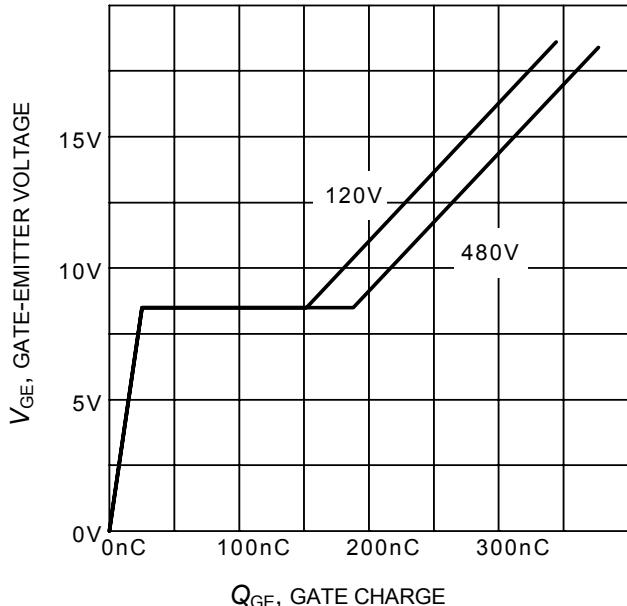

 Q_{GE} , GATE CHARGE

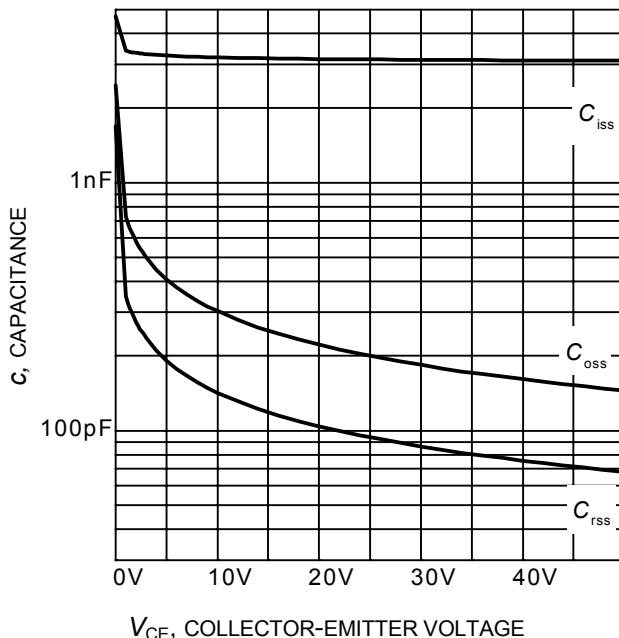
Figure 17. Typical gate charge
($I_C=50$ A)

 V_{CE} , COLLECTOR-EMITTER VOLTAGE

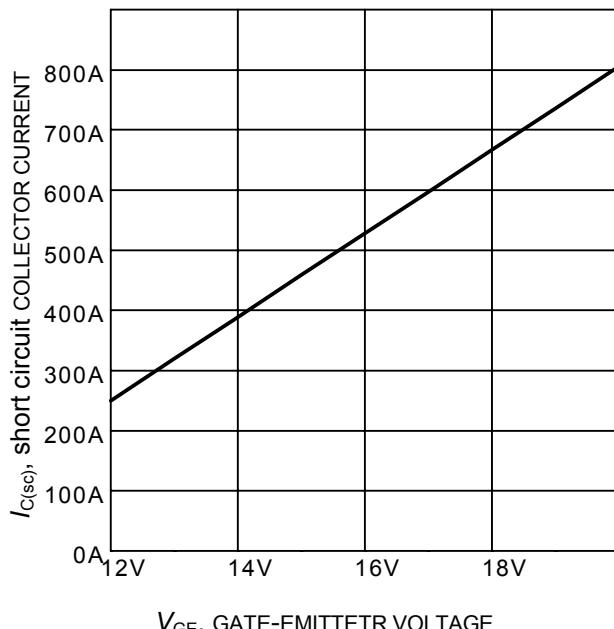
Figure 18. Typical capacitance as a function
of collector-emitter voltage
($V_{GE}=0$ V, $f = 1$ MHz)

 V_{GE} , GATE-EMITTER VOLTAGE

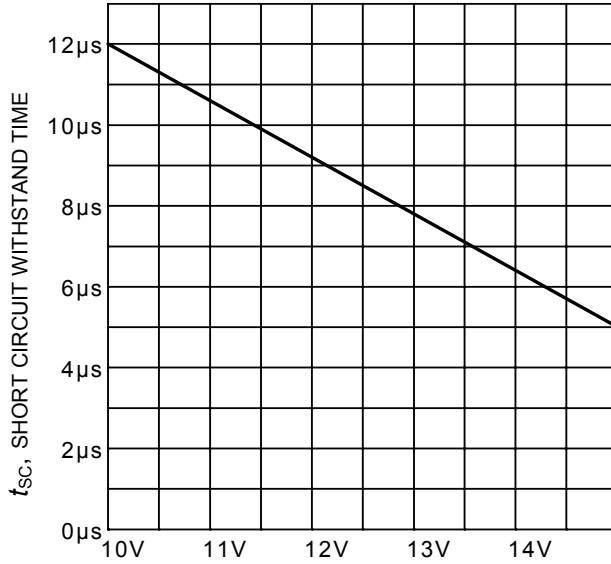
Figure 19. Typical short circuit collector current as a function of gate-emitter voltage
($V_{CE} \leq 400$ V, $T_j \leq 150^\circ\text{C}$)

 V_{GE} , GATE-EMITTER VOLTAGE

Figure 20. Short circuit withstand time as a function of gate-emitter voltage
($V_{CE}=600$ V, start at $T_j=25^\circ\text{C}$,
 $T_{jmax}<150^\circ\text{C}$)

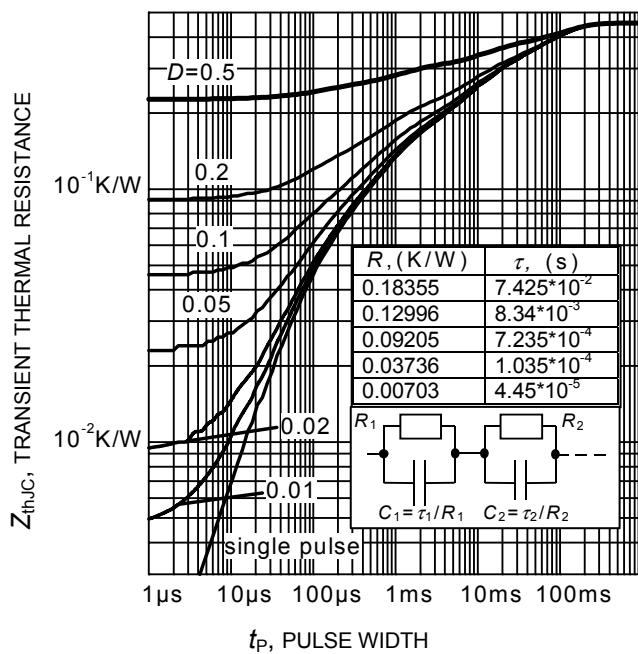
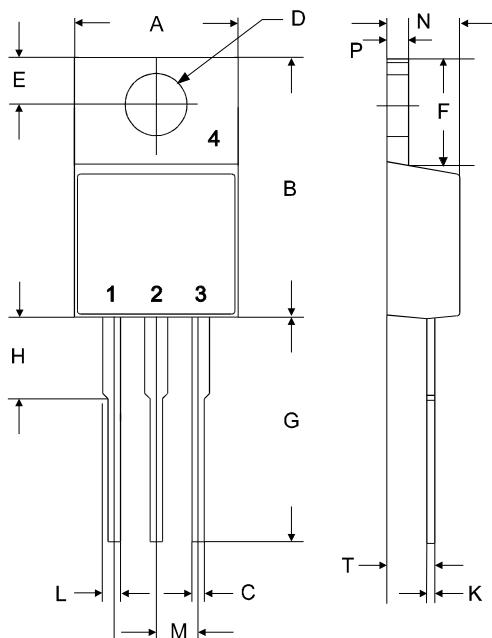
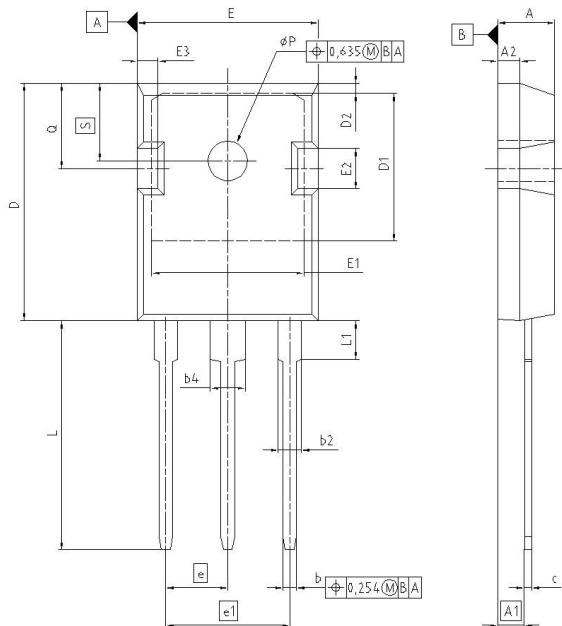


Figure 21. IGBT transient thermal resistance
 $(D = t_p / T)$

PG-T0220-3-1



PG-T0247-3-21



symbol	Dimensions			
	[mm]		[inch]	
	min	max	min	max
A	9.70	10.30	0.3819	0.4055
B	14.88	15.95	0.5858	0.6280
C	0.65	0.86	0.0256	0.0339
D	3.55	3.89	0.1398	0.1531
E	2.60	3.00	0.1024	0.1181
F	6.00	6.80	0.2362	0.2677
G	13.00	14.00	0.5118	0.5512
H	4.35	4.75	0.1713	0.1870
K	0.38	0.65	0.0150	0.0256
L	0.95	1.32	0.0374	0.0520
M	2.54 typ.		0.1 typ.	
N	4.30	4.50	0.1693	0.1772
P	1.17	1.40	0.0461	0.0551
T	2.30	2.72	0.0906	0.1071

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.092	0.096
A2	1.853	2.107	0.075	0.081
b	1.073	1.327	0.047	0.052
b2	1.903	2.386	0.075	0.094
b4	2.870	3.454	0.113	0.136
c	0.549	0.752	0.024	0.030
D	20.823	21.077	0.820	0.830
D1	17.323	17.831	0.682	0.702
D2	1.063	1.317	0.042	0.052
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
E2	3.663	3.937	0.145	0.155
E3	1.683	1.937	0.066	0.076
e	5.450		0.215	
e1	10.900		0.430	
N	3		3	
L	20.053	20.307	0.789	0.799
L1	4.168	4.472	0.164	0.176
oP	3.559	3.661	0.140	0.144
Q	5.493	5.747	0.216	0.226
S	6.043	6.297	0.238	0.248

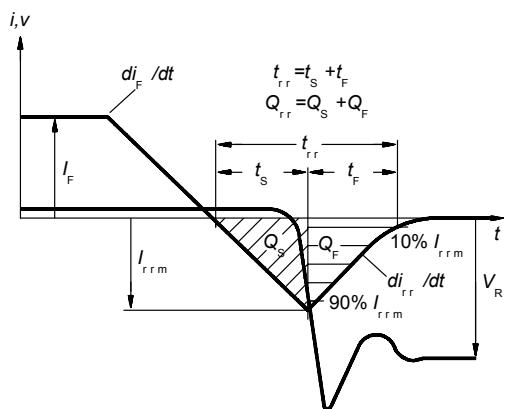
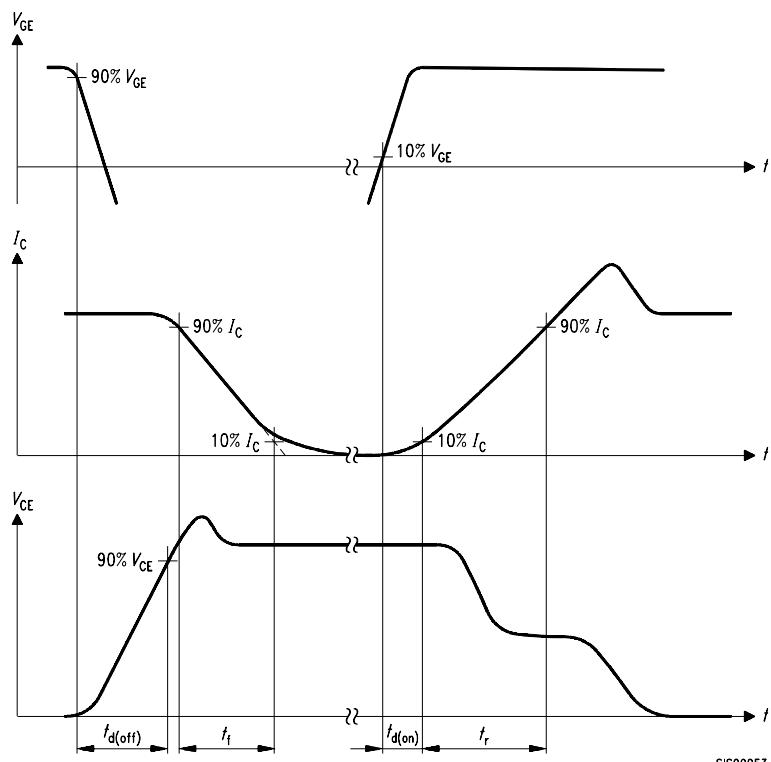


Figure C. Definition of diodes switching characteristics

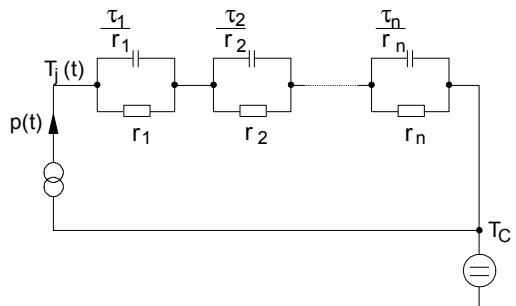


Figure D. Thermal equivalent circuit

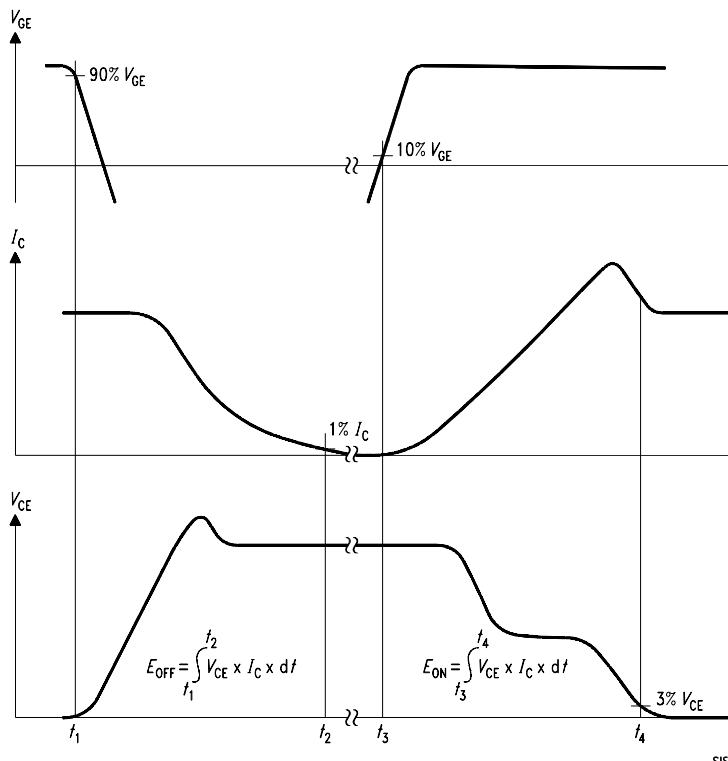


Figure B. Definition of switching losses

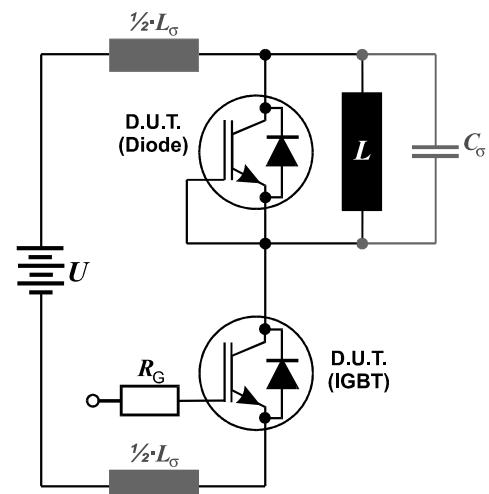


Figure E. Dynamic test circuit



TrenchStop® Series

IGP50N60T
IGW50N60T

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